

Title:            WAFER LIFT DEVICE

Use Space Below for Additional Information:

In the Specification:

The top of page 1, please amend as follows:.

(Currently Amended) Be it known that WE, Rüdiger Hunger, Steffen Herberg and Falk Bednara, citizens of Germany, respectively, whose post office addresses are Hansastraße 35, D-01097 01097 Dresden, Germany; Steinbacher Weg 23C, D-01723 ~~Kesselsdorf~~ Kesselsdorf, Germany and Mengsstraße 21, D-01139 Dresden, Germany, respectively, have invented an improvement in

(Currently Amended) [0004] The wafer receptacle may be designed as a heating plate. In particular, such heating plates are used during the process step of resist incineration. During this process step, the wafers are heated by means of the heating plate, and the hot wafers are exposed to an oxygen atmosphere. As a result, the photoresist of a ~~photoresist~~ photoresist mask which is situated on the wafer oxidizes to form a volatile gas and burns without any residue.

(Currently Amended) [0020] Another possibility for the connection of the cylindrical body to the wafer receptacle is that the cylindrical body, at a side perpendicular to the center axis of the guide hole, is provided with a flange having fastening holes corresponding to screw connections in the wafer receptacle. This solution is favorable in particular when the wafer receptacle is configured as a heating plate, since here larger tolerances of the individual components are possible and, consequently, it is possible to avoid jamming on account of different thermal expansions.